



Europäisches Patentamt  
European Patent Office  
Office européen des brevets

⑪ Publication number:

0 313 961  
A2

⑫

## EUROPEAN PATENT APPLICATION

⑬ Application number: 88117300.9

⑮ Int. Cl.4: H05K 1/03, B32B 5/28,  
C08J 5/04, //C08L27/12

⑭ Date of filing: 18.10.88

⑬ Priority: 26.10.87 US 113533

⑯ Applicant: ROGERS CORPORATION  
Main Street  
Rogers, Conn. 06263(US)

⑭ Date of publication of application:  
03.05.89 Bulletin 89/18

⑰ Inventor: McGinnis, Leon W.

⑬ Designated Contracting States:  
BE DE FR GB IT NL SE

deceased(US)

Inventor: Carroll, James R.  
418 Barbara Drive  
Tempe Arizona 85281(US)  
Inventor: Miller, Terry L.  
11233 South 163rd Street  
Gilbert Arizona 85234(US)  
Inventor: Norris, Michael B.  
12611 East Ballejo  
Chandler Arizona 85249(US)

⑬ Designated Contracting States:  
BE DE FR GB IT NL SE

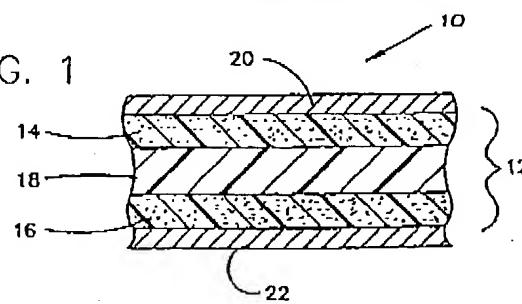
⑰ Representative: Meyers, Ernest et al  
Office de Brevets Freylinger & Associés 46  
rue du Cimetière B.P. 1153  
L-1011 Luxembourg(LU)

⑩ Glass fiber reinforced fluoropolymeric circuit laminate.

⑩ A fluoropolymeric circuit laminate consisting of one or more layers of fluoropolymer impregnated woven glass cloth sandwiched between one or more layers of "random" microfiberglass reinforced fluoropolymer is presented. This composite of fluoropolymer, woven glass fabric and random glass microfibers may be clad on one or both outer surfaces with a suitable conductive material such as copper or certain known resistive foils. The fluoropolymer impregnated woven glass layer of layers will be nested between microfiberglass reinforced fluoropolymer layers to provide the outer surfaces of the circuit with smooth surfaces for fine line circuitry. The circuit laminate of the present invention exhibits good dimensional stability, smooth surfaces for fine line circuitry, good electrical properties, and strong foil and interlaminar adhesion properties.

EP 0 313 961 A2

FIG. 1



EP 0 313 961 A2

## GLASS FIBER REINFORCED FLUOROPOLYMERIC CIRCUIT LAMINATE

This invention relates to laminated circuit materials. More particularly, this invention relates to fluoropolymeric glass reinforced circuit materials having excellent dimensional stability, electrical properties and a smooth surface. This circuit material is particularly well suited for applications requiring microwave 5 operating frequencies.

Most common printed wiring board materials undergo dimensional changes during processing. These changes are induced by stress relaxation as metal claddings are removed and/or by absorption with processing solutions, and/or by temperature, pressure or humidity excursions. The addition of reinforcing fibers to polymer systems is intended, in part, to reduce the dimensional changes that occur during 10 processing.

With respect to glass reinforced fluoropolymer boards, particularly boards composed of polytetrafluoroethylene (PTFE), there have been three common prior art types.

15 Type 1

The first type contemplates the use of a homogeneous dielectric layer of random microfiber glass reinforced PTFE. This approach produces a laminate with superior electrical performance, primarily 20 because of the low weight percent of glass present. These random microfiberglass reinforced PTFE materials have smooth surfaces for the production of fine line circuitry needed in microwave applications. However, of the three common PTFE laminate types, it has the largest dimensional change upon 25 processing. It will be appreciated that the lack of dimensional stability is a significant drawback as there are many well known problems associated with poor dimensional stability. One particularly troublesome problem involves the necessity for a double etching procedure. Such a procedure involves creation of two sets of artwork, the initial set processing geometries larger than that desired. After photoimaging and 30 etching, much of the dimensional change will be realized. The final artwork is then photoimaged and etched. It will be appreciated that this double etching procedure leads to significantly higher costs due to additional labor, materials (e.g. photoimagineable photoresist, etching solution), artwork costs and associated handling damage. Random glass fiber reinforced circuit boards of this type have a dielectric constant of 2.20 to 2.33, are well known in the art by the designations GR and GP; and are specified to military 35 designation MIL-P-13949/7E.

35 Type 2

The second type of circuit material involves the use of PTFE impregnated woven glass cloths and produces a laminate exhibiting a higher dissipation factor than that described in the first type. Such 40 laminates typically possess better dimensional stability than those described above principally because of the presence of continuous glass fibers (rather than short, discontinuous microfibers). These materials have a dielectric constant of 2.4 to 2.6 and are known in the art by the designation GX and GT. GX and GT materials are specified in MIL-P-13949/14A.

45 Type 3

The third type of fluoropolymer circuit materials comprise composites consisting of alternating layers of unreinforced PTFE (i.e., no glass filler) and PTFE impregnated woven glass cloth. This third type offers low 50 dielectric constant, dissipation factor, and improved dimensional stability relative to type GR materials. However, because of the presence of unreinforced layers of PTFE, the laminate suffers from poor foil adhesion and interlaminar or interstitial delamination problems. Such laminates also do not withstand thermal cycling, thermal stress or molten solder temperatures without significant bond degradation. Because of the poor foil adhesion, copper peel strength drops substantially after temperature excursions such as those associated with multilayer bonding or temperature cycling. These laminates also suffer from significant changes in z-axis dielectric constant because of the stratified construction. These laminates have dielectric contents of about 2.17 and are designated as MIL-P-13949/14A type GY.

## EP 0 313 961 A2

While all of the above discussed types of fluoropolymers circuit materials include certain advantageous and desirable features, each also suffers from certain limitations and drawbacks. Unfortunately, there is presently no one glass reinforced fluoropolymers circuit material which combines the best features of the known materials (e.g., good dimensional stability, good electrical properties and smooth surfaces for fine line production) without some of the problems associated with these prior art materials.

The purpose of the present invention is to overcome or alleviate the above-discussed and other deficiencies and drawbacks of the prior art. In accordance with the present invention, a circuit laminate is provided which is composed of one or more layers of fluoropolymer impregnated woven glass cloth sandwiched between one or more layers of "random" microfiberglass reinforced fluoropolymer. This composite of fluoropolymer, woven glass fabric and random glass microfibers may be clad on one or both outer surfaces with a suitable conductive material such as copper or certain known resistive foils. The fluoropolymer impregnated woven glass layer or layers will be nested between microfiberglass reinforced fluoropolymer layers to provide the outer surfaces of the circuit with smooth surfaces for fine line circuitry.

The circuit laminate of the present invention combines all of the best qualities of known fluoropolymer circuit materials without any of the various disadvantages. For example, the present invention exhibits good dimensional stability (like GX, GT and GY), smooth surfaces for fine line circuitry (like GR, GP), good electrical properties (like GR, GP, GY) and strong foil and interlaminar adhesion properties (unlike GY).

The above-discussed and other features and advantages of the present invention will be appreciated and understood by those skilled in the art from the following detailed description and drawings.

20 Referring now to the drawings wherein like elements are numbered alike in the several FIGURES :

FIGURE 1 is a cross sectional elevation view of a circuit laminate in accordance with the present invention;

FIGURE 2 is a cross sectional elevation view of another circuit laminate in accordance with the present invention; and

25 FIGURE 3 is a cross sectional elevation view of still another circuit laminate in accordance with the present invention.

Referring first to FIGURE 1, a fluoropolymer composite circuit laminate in accordance with the present invention is identified at 10. Generally, the dielectric substrate 12 of circuit laminate 10 comprises glass 30 microfiber reinforced fluoropolymer layers interleaved with at least one layer of fluoropolymer impregnated woven glass cloth. The total dielectric thickness will preferably range from 0.076 mm to 12.7 mm. In the particular embodiment of the present invention depicted in FIGURE 1, a relatively simple dielectric construction is shown including a pair of microglass fiber reinforced fluoropolymer layers 14 and 16 sandwiching therebetween a layer 18 of fluoropolymer impregnated woven glass cloth. However, it will be appreciated that layers 14, 16 and 18 may be comprised of multiple layers or plies of the respective glass/fluoropolymer composites.

The dielectric substrate 12 includes one or two conductive layers on its opposed outer surfaces. In the FIGURE 1 embodiment, two conductive layers 20 and 22 are provided on the exposed surfaces of dielectric layers 14 and 16. Conductive layers 20 and 22 may be comprised of a suitable conductive metal such as 40 copper. Alternatively, the conductive layers may include portions of known resistive foils such as the type disclosed in U.S. Patent No 3,808,576, which is incorporated herein by reference; and which is commercially available under the trademark "Ohmega-Ply Foil".

The fluoropolymers material used in both the microfiber glass and woven glass layers 14, 16 and 18 is preferably polytetrafluoroethylene (PTFE). However, other fluoropolymers materials could also be used including, but not limited to a copolymer of tetrafluoroethylene and perfluoralkyl vinyl ether (PFA), a copolymer of hexafluoropropylene and tetrafluoroethylene (FEP) and a copolymer of tetrafluoroethylene and ethylene (Tefzel).

50 Preferably, the length, diameter and percentage of glass fibers (which may consist of commercially available E-glass) in the homogeneously and randomly dispersed microfiber glass reinforced fluoropolymer layers (e.g. layers 14 and 16) will vary within the following ranges :

Length: less than 5000 micrometers

Diameter: 0.3 to 0.7 micrometers

Weight percentage: 2 % to 25 %

55 Preferably, the fluoropolymer impregnated woven glass cloth layer (e.g. layer 18) will consist of a suitable commercially available weave of E-glass with weight percent of fluoropolymer of between about 30 % to about 85 %. These weaves may include, in addition to style 1080, styles 108, 106, 112 and similar styles. All of the style numbers are common industry designations.

As mentioned, the structure of the laminate of the present invention consists of one or more layers of

## EP 0 313 961 A2

fluoropolymer impregnated woven glass cloth separated by one or more layers of random microfiber reinforced fluoropolymer. The fluoropolymer impregnated woven glass cloth will preferably comprise from about 10 % to 60 % of the overall laminate thickness, exclusive of claddings.

In FIGURE 2, a more complex embodiment of the present invention is shown generally at 24. Circuit 5 laminate 24 comprises a similar dielectric substrate 12, but additionally includes upper and lower fluoropolymeric (e.g. PTFE) bonding layers 26 and 28 on glass reinforced fluoropolymer layers 14' and 16' respectively. These bounding films 26, 28 are quite thin (e.g. 0.025 mm thick) and are used to improve the adhesion with the metal cladding. The embodiment of FIGURE 2 further includes an upper outer layer 30 comprising a known resistive foil which consists of a resistive layer plated onto a copper foil; and a lower outer layer 32 comprising a suitable conductive foil such as copper. The structure of circuit laminate 24 is 10 discussed in more detail hereinafter with regard to example I.

Still another embodiment of the present invention is shown generally at 34 in FIGURE 3. Circuit laminate 34 is substantially similar to circuit laminate 24 of FIGURE 2. The only difference between the circuits is that laminate 34 includes an additional layer 36 of fluoropolymer impregnated woven glass and an 15 additional layer 38 of microglass reinforced fluoropolymer. Note that woven glass layer 36 is sandwiched between random microglass layers 16' and 38. FIGURE 3 will be discussed in more detail with regard to Examples 6, 7, 12 and 13.

The following are non-limited examples of the circuit laminate of the present invention :

20

Example 1

The circuit laminate used for the first example has an overall construction as shown in FIGURE 2. The following is a detailed description of each of the layers in the laminate composite with reference to the 25 identifying numerals of FIGURE 2.

The microglass reinforced layers 14' and 16' are RT/duroid 5880® a commercially available material manufactured by Rogers Corporation. RT/duroid 5880® is a glass microfiber reinforced PTFE composite having a random homogeneous dispersion of glass microfibers within the ranges described hereinabove. In the construction described above, the microglass reinforced layers 14' and 16' comprise a total of 3,80 mm 30 of the 5 mm of dielectric, or 1,90 mm per side.

The woven glass layer 18 is polytetrafluoroethylene (PTFE) coated commercially available woven glass fabric. The glass reinforcement is a woven glass fabric comprised of E-glass woven in style 1080 (a common industry designation). The PTFE comprised 76 % of the weight of the PTFE coated woven glass fabric, the remaining portion is the E-glass. In the above construction, the PTFE impregnated, woven glass 35 comprises 0,076 mm of the 0,50 mm total thickness.

The PTFE bonding films 26 and 28 are commercially available skived or cast PTFE films 0,025 mm thick. These films are 100 % PTFE (no glass, or other, reinforcements). These films improve mechanical adhesion of metal claddings because of their lower melt viscosity. In the construction described above, the 40 films account for a total of 0,050 mm (two pieces of 0,025 mm film) out of a total dielectric thickness of 0,05 mm.

Resistive layer 30 is Ohmega foil, a commercially available resistive foil available from Ohmega Technologies. The foil consists of a resistive layer plated onto a copper foil.

Conductive layer 32 is a copper foil which is a commercially available electrodeposited foil meeting IPC specification #IPC-CF-150E. Foil weight is 28 g (nominal thickness 0,035 mm).

45 In Table 1, a data summary for the circuit laminate of Example 1 is set forth for three different lots (A-C). This data is compared to the same properties of a standard microfiber glass reinforced circuit (RT/duroid 5880®). As is clear from Table 1, the circuit laminate of the present invention has a low dielectric constant (2,222 to 2,229) and excellent dimensional stability, especially when compared to prior art type GR materials (e.g. RT/duroid 5880®).

50

55

EP 0 313 961-A2

Table 1

|                                    | Present Invention<br>Example 1(A) | Present Invention<br>Example 1 (B) | Present Invention<br>Example 1 (C) | RT/duroid<br>5880 ® |
|------------------------------------|-----------------------------------|------------------------------------|------------------------------------|---------------------|
| MIIP DR                            | 2,225                             | 2,222                              | 2,229                              | 2,185               |
| MIIP DF                            | 0,00101                           | 0,00105                            | 0,00104                            | 0,00109             |
| Sp G (specific<br>gravity)         | 2,213                             | 2,211                              | 2,207                              | 2,206               |
| Thickness (mm)                     | 0,0200                            | 0,0199                             | 0,0209                             | 0,0199              |
| Peel Strength<br>kg/cm Solder      | 1,99                              | 2,06                               | 1,96                               | 2,00                |
| Dimensional <sup>1</sup>           |                                   |                                    |                                    |                     |
| Stability (μ/mm)                   |                                   |                                    |                                    |                     |
| - MD (Machine<br>direction)        | -0,1239                           | -0,1198                            | -0,1574                            | -0,9185             |
| - CMD (Cross<br>Machine Direction) | -0,6198                           | -0,6867                            | -0,5034                            | -3,7169             |
| Tensile Strength                   |                                   |                                    |                                    |                     |
| - MD                               | 7426,70                           | 7738,90                            | 7966,50                            | 5176,53             |
| - CMD                              | 6934,19                           | 6763,22                            | 7381,25                            | 4431,87             |
| Elongation                         |                                   |                                    |                                    |                     |
| - MD                               | 5,75                              | 6,00                               | 6,00                               | 15,50               |
| - CMD                              | 6,75                              | 7,00                               | 7,25                               | 25,00               |

<sup>1</sup> Measured at room temperature after Cu removed @ hr. @ 170°C.

5a

Examples 2-13

In the following examples, the same overall structure of FIGURE 2 has been used, however certain variations and changes in material percentages and compositions have been made. The changes are as follows:

The microglass layers 14, 16' of the laminate is RT/duroid 5870® commercially available from Rogers Corporation (rather than RT/duroid 5880 ® used in Example 1). Laminates with total dielectric thickness of 0,25 mm through 1,575 mm have been evaluated. The amount of microglass reinforced dielectric (item 12'

## EP 0 313 961 A2

in FIGURE 2) used in these laminates varied from 0.15 mm (in the case of the 2.5 mm laminate), to 1.40 mm (in the case of the 1.575 mm laminate). See the attached table 2 for detailed information on the compositional percentages of each component.

The PTFE bonding films 26 and 28 used in these laminates were as described above, but varied in thickness from 0.0127 mm to 0.05 mm. See the attached table 2 for more details.

The PTFE coated woven glass fabric 18 used in these laminations was identical to that used for the laminations described above in example 1.

In addition to the evaluations of the above-noted structures, a composite based on the laminate depicted in FIGURE 3 was also evaluated. Reference should be made to table 2 for a detailed analysis of the composition of the FIGURE 3 laminates which correspond to Examples 6, 7, 12 and 13.

15

20

25

30

35

40

45

50

55

EP 0 313 961 A2

Table 2

| Example | Thickness (mm) | Microglass Type | Total THK (mm) | # Ply Woven Glass Fiber <sup>2</sup> | Total THK PTFE Bonding Film <sup>3</sup> (mm) |
|---------|----------------|-----------------|----------------|--------------------------------------|---|
| 2       | 0,25           | 5880            | 0,15           | 1                                    | 0,025   |
| 3       | 0,50           | 5880            | 0,38           | 1                                    | 0,05  |
| 4       | 0,79           | 5880            | 0,66           | 1                                    | 0,05  |
| 5       | 1,575          | 5880            | 1,40           | 1                                    | 0,10  |
| 6       | 0,79           | 5880            | 0,58           | 2                                    | 0,05  |
| 7       | 1,575          | 5880            | 1,32           | 2                                    | 0,10  |
| 8       | 0,25           | 5870            | 0,15           | 1                                    | 0,025   |
| 9       | 0,50           | 5870            | 0,38           | 1                                    | 0,05  |
| 10      | 0,79           | 5870            | 0,66           | 1                                    | 0,05  |
| 11      | 1,575          | 5870            | 1,40           | 1                                    | 0,10  |
| 12      | 0,79           | 5870            | 0,58           | 2                                    | 0,05  |
| 13      | 1,575          | 5870            | 1,32           | 2                                    | 0,10  |

{1} In the cases of laminates produced with 1 ply of woven glass fabric (FIGURE 2), the total thickness of microglass reinforced dielectric is split two ways. In the case where two plies of woven glass fabric are used (FIGURE 3), the microglass reinforced dielectric material is split 3 ways.

{2} All plies of woven glass are 0,076 mm; however, this may vary with other fabric styles.

{3} One ply of film is always used on each side, thus each ply is  $\frac{1}{2}$  of the total thickness shown below.

EP 0 313 961 A2

Table 3

| Example               | 2      | 3      | 4        | 5        | 6      | 7      | 8      | 9      | 10     | 11     | 12     | 13     |
|-----------------------|--------|--------|----------|----------|--------|--------|--------|--------|--------|--------|--------|--------|
| HiIP DK               | 2.262  | 2.233  | 2.225    | 2.213    | 2.249  | 2.221  | 2.347  | 2.356  | 2.355  | 2.342  | 2.361  | 2.350  |
| HiIP DF               | .00120 | .00101 | .00103   | .00092   | .00109 | .00092 | .00154 | .00172 | .00160 | .00144 | .00156 | .00151 |
| Sp Q                  | 2.190  | 2.204  | 2.186    | 2.193    | -      | -      | 2.207  | 2.196  | 2.203  | 2.195  | 2.204  | 2.199  |
| Thickness (mm)        | 0.25   | 0.48   | 0.76     | 1.56     | 0.76   | 1.56   | 0.24   | 0.49   | 0.77   | 1.58   | 0.77   | 1.57   |
| Peel Strength         |        |        |          |          |        |        |        |        |        |        |        |        |
| Solder (kg/cm)        | 2.80   | 2.07   | 2.46     | 2.12     | 2.73   | 2.28   | 3.27   | 3.53   | 3.29   | 2.75   | 3.56   | 2.25   |
| Dimensional Stability |        |        |          |          |        |        |        |        |        |        |        |        |
| - DK                  | .4571  | -.0811 | -.2331   | -.4910   | .1023  | -.1141 | .6422  | .2129  | .2718  | .1345  | .3238  | .2110  |
| - CND                 | .1145  | -.7265 | -.1.0722 | -.1.6563 | -.1811 | -.8536 | .4010  | -.0133 | -.1515 | -.1162 | .2643  | -.0126 |

Units are in  $\mu$  per mm. After complete copper removal and two 1 hr. 170°C stress relieving bakes.

The electrical and mechanical properties of Examples 2-13 are set forth in Table 3 and are in accordance with the results set forth in table I.

As is clear from a review of the foregoing results, the circuit laminate of the present invention provides all of the advantages of the prior art fluoropolymeric materials discussed above in the background section (e.g. improved dimensional stability, smooth surface for fine lines, good electrical properties including low dielectric constant, low dissipation factor and good surface isotropy) without any of the various deficiencies

EP 0 313 961 A2

and drawbacks of these prior materials. Moreover, the circuit laminate of the present invention may, in some instances, preclude the necessity for double etching procedures because of its improved dimensional stability. The circuit laminate of the present invention also exhibit strong foil and interlaminar adhesion properties.

5

## Claims

1. A circuit substrate laminate comprising:
  - 10 at least one first layer (18) of a fluoropolymer impregnated woven glass cloth having opposed first and second surfaces;
  - 14 at least one first layer (14) of a random microglass reinforced fluoropolymer on said first surface of said first layer (18) of fluoropolymer impregnated woven glass cloth; and
  - 16 at least one second layer (16) of a random microglass reinforced fluoropolymer on said second surface of said first layer of fluoropolymer impregnated woven glass cloth.
2. A laminate as claimed in claim 1, wherein each of said first and second microglass reinforced fluoropolymer layers (14,16) includes an exposed surface opposite said at least one layer (18) of fluoropolymer impregnated woven glass cloth and including:
  - 20 conductive material (20,22) on at least a portion of at least one of said exposed surfaces of said first and second layers (14,16) of microglass reinforced fluoropolymer.
  3. A laminate as claimed in claim 2, wherein said conductive material is copper.
  4. A laminate as claimed in claim 2, wherein said conductive material is a resistive foil.
  5. A laminate as claimed in claim 1, wherein said fluoropolymer is at least one of the fluoropolymers selected from the group consisting of:
  - 25 polytetrafluoroethylene, a copolymer of tetrafluoroethylene and perfluoroalkyl vinyl ether, a copolymer of hexafluoropropylene and tetrafluoroethylene or a copolymer of tetrafluoroethylene and ethylene.
  6. A laminate as claimed in claim 1, wherein said fluoropolymer impregnated woven glass cloth layer has about 30 to 85 weight percent of fluoropolymer.
  7. A laminate as claimed in claim 1, wherein said at least one fluoropolymer impregnated woven glass cloth layer comprises about 10 to 60 percent of the total laminate thickness.
  - 30 8. A laminate as claimed in claim 1, wherein said microglass is microfiberglass and wherein said microfiberglass has a length of less than 5000 micrometers and a diameter of between about 0.3 to 0.7 micrometers.
  9. A laminate as claimed in claim 1 or 8, wherein each of said layers of microglass reinforced fluoropolymer comprises about 2 to 25 weight percent of microglass.
  - 35 10. A laminate as claimed in claim 1, wherein said laminate has a total thickness of between about 0.076 to 12.7 mm.
  11. A laminate as claimed in claim 2, including:
    - 40 a fluoropolymeric bonding layer between said conductive material and said layer of microglass reinforced fluoropolymer.

45

50

55

EP 0 313 961 A2

FIG. 1

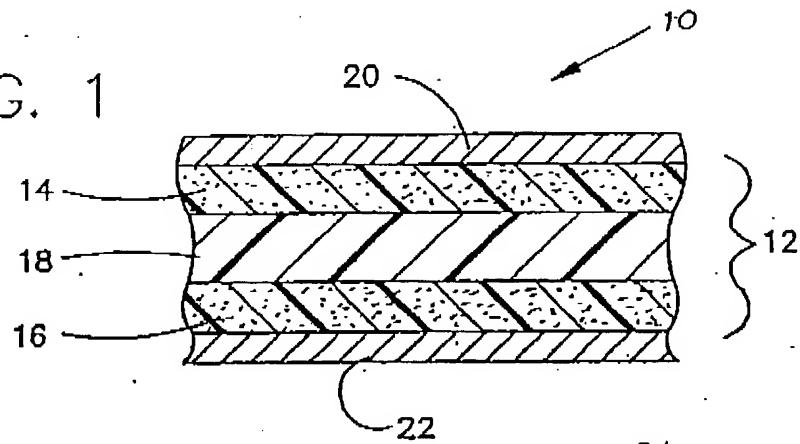


FIG. 2

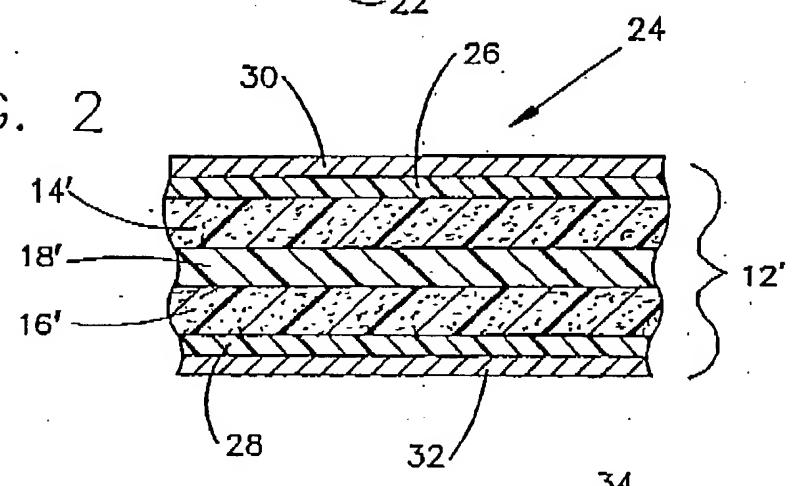
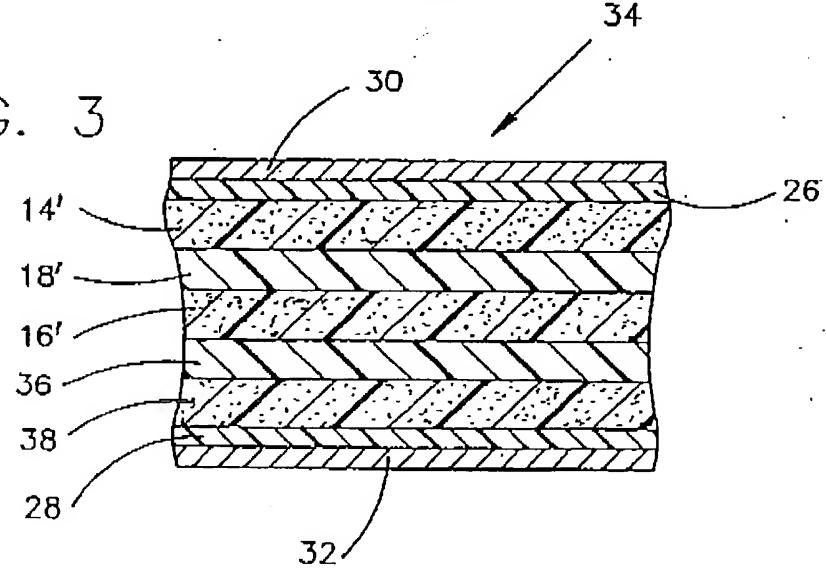


FIG. 3





(11) Publication number:

0 313 961  
A3

(12)

## EUROPEAN PATENT APPLICATION

(21) Application number: 88117300.9

(51) Int. CL5: H05K 1/03, B32B 5/28,  
C08J 5/04, //C08L27/12

(22) Date of filing: 18.10.88

(30) Priority: 26.10.87 US 113533

(71) Applicant: ROGERS CORPORATION  
Main Street  
Rogers, Conn. 06263(US)(43) Date of publication of application:  
03.05.89 Bulletin 89/18

(72) Inventor: McGinnis, Leon W.

(84) Designated Contracting States:  
BE DE FR GB IT NL SE

deceased(US)  
 Inventor: Carroll, James R.  
 418 Barbara Drive  
 Tempe Arizona 85281(US)  
 Inventor: Miller, Terry L.  
 11233 South 163rd Street  
 Gilbert Arizona 85234(US)  
 Inventor: Norris, Michael B.  
 12611 East Ballejo  
 Chandler Arizona 85249(US)

(86) Date of deferred publication of the search report:  
05.09.90 Bulletin 90/36(73) Representative: Meyers, Ernest et al  
Office de Brevets FREYLINGER & ASSOCIES  
B.P. 1 321, route d'Arlon  
L-8001 Strassen(LU)

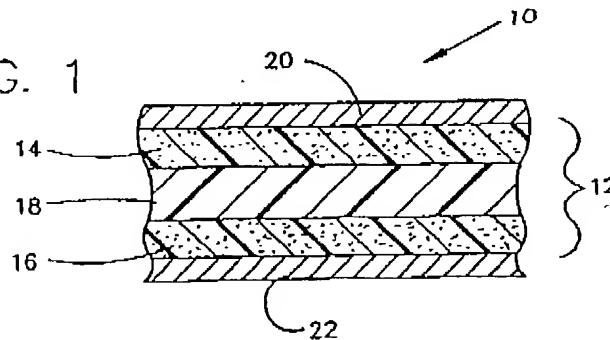
(54) Glass fiber reinforced fluoropolymeric circuit laminate.

(57) A fluoropolymeric circuit laminate consisting of one or more layers of fluoropolymer impregnated woven glass cloth (18) sandwiched between one or more layers (14,16) of "random" microfiberglass reinforced fluoropolymer is presented. This composite

of fluoropolymer, woven glass fabric and random glass microfibers may be clad on one or both outer surfaces with a suitable conductive material (20,22) such as copper or certain known resistive foils.

EP 0 313 961 A3

FIG. 1





European Patent  
Office

## EUROPEAN SEARCH REPORT

Application Number

EP 88 11 7300

| DOCUMENTS CONSIDERED TO BE RELEVANT  |   |                     |
|--|---|---------------------|
| Category   | Citation of document with indication, where appropriate, of relevant passages | Relevant to claim   |
| A  | EP-A-0 217 311 (KANEGAFUCHI KAGAKU KOGYO K.K.)<br>-----                       |                     |
| A  | US-A-4 634 631 (ROGERS CORP.)<br>-----  |                     |
| A  | US-A-3 393 117 (CINCINNATI MILLING MACHINE)<br>-----                          |                     |
| A  | EP-A-0 160 439 (JUNKOSHA CO., LTD)<br>-----                                   |                     |
| TECHNICAL FIELDS<br>SEARCHED (Int. Cl.4)   |   |                     |
| H 05 K<br>B 32 B   |   |                     |
| The present search report has been drawn up for all claims   |   |                     |
| Place of search  | Date of completion of the search  | Examiner            |
| THE HAGUE  | 11-06-1990  | SCHUERMANS N. F. G. |
| CATEGORY OF CITED DOCUMENTS  |   |                     |
| X : particularly relevant if taken alone<br>Y : particularly relevant if combined with another document of the same category<br>A : technological background<br>O : non-written disclosure<br>P : intermediate document  |   |                     |
| T : theory or principle underlying the invention<br>E : earlier patent document, but published on, or after the filing date<br>D : document cited in the application<br>L : document cited for other reasons<br>& : member of the same patent family, corresponding document |   |                     |